

1.5V Drive Pch MOSFET

RW1A013ZP

●Structure

Silicon P-channel MOSFET

●Features

- 1) Low on-resistance.
- 2) High power package.
- 3) Low voltage drive. (1.5V)

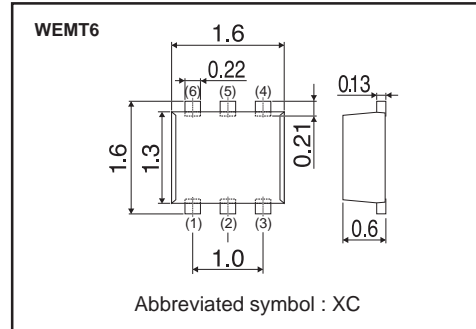
●Application

Switching

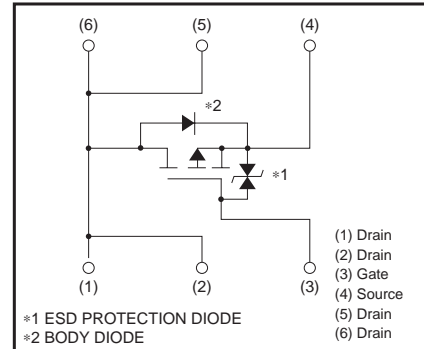
●Packaging specifications

| Type | Package | Taping |
|-----------|------------------------------|--------|
| | Code | T2R |
| | Basic ordering unit (pieces) | 8000 |
| RW1A013ZP | | ○ |

●Dimensions (Unit : mm)



●Inner circuit



●Absolute maximum ratings (Ta=25°C)

| Parameter | Symbol | Limits | Unit | |
|------------------------------|------------|-------------|------|---|
| Drain-source voltage | V_{DSS} | -12 | V | |
| Gate-source voltage | V_{GSS} | ±10 | V | |
| Drain current | Continuous | I_D | ±1.3 | A |
| | Pulsed | I_{DP} *1 | ±2.6 | A |
| Source current (Body diode) | Continuous | I_S | -0.5 | A |
| | Pulsed | I_{SP} *1 | -2.6 | A |
| Total power dissipation | P_D *2 | 0.7 | W | |
| Channel temperature | T_{ch} | 150 | °C | |
| Range of Storage temperature | T_{stg} | -55 to +150 | °C | |

*1 $P_w \leq 10\mu s$, Duty cycle $\leq 1\%$

*2 When mounted on a ceramic board

●Thermal resistance

| Parameter | Symbol | Limits | Unit |
|--------------------|------------------|--------|--------|
| Channel to ambient | $R_{th(ch-a)}$ * | 179 | °C / W |

* When mounted on a ceramic board

●Electrical characteristics (Ta=25°C)

| Parameter | Symbol | Min. | Typ. | Max. | Unit | Conditions |
|-----------------------------------------|------------------------|------|------|------|------|-------------------------------------------------|
| Gate-source leakage | I _{GSS} | - | - | ±10 | μA | V _{GS} =±10V, V _{DS} =0V |
| Drain-source breakdown voltage | V _{(BR) DSS} | -12 | - | - | V | I _D = -1mA, V _{GS} =0V |
| Zero gate voltage drain current | I _{DSS} | - | - | -1 | μA | V _{DS} = -12V, V _{GS} =0V |
| Gate threshold voltage | V _{GS (th)} | -0.3 | - | -1.0 | V | V _{DS} = -6V, I _D = -1mA |
| Static drain-source on-state resistance | R _{DS (on)} * | - | 190 | 260 | mΩ | I _D = -1.3A, V _{GS} = -4.5V |
| | | - | 280 | 390 | mΩ | I _D = -0.6A, V _{GS} = -2.5V |
| | | - | 400 | 600 | mΩ | I _D = -0.6A, V _{GS} = -1.8V |
| | | - | 530 | 1060 | mΩ | I _D = -0.2A, V _{GS} = -1.5V |
| Forward transfer admittance | Y _{fs} * | 1.4 | - | - | S | V _{DS} = -6V, I _D = -1.3A |
| Input capacitance | C _{iss} | - | 290 | - | pF | V _{DS} = -6V |
| Output capacitance | C _{oss} | - | 28 | - | pF | V _{GS} =0V |
| Reverse transfer capacitance | C _{rss} | - | 21 | - | pF | f=1MHz |
| Turn-on delay time | t _{d (on)} * | - | 8 | - | ns | V _{DD} ≐ -6V |
| Rise time | t _r * | - | 10 | - | ns | I _D = -0.6A |
| Turn-off delay time | t _{d (off)} * | - | 30 | - | ns | V _{GS} = -4.5V |
| Fall time | t _f * | - | 9 | - | ns | R _L ≐ 10Ω |
| Total gate charge | Q _g * | - | 2.4 | - | nC | V _{DD} ≐ -6V R _L ≐ 4.6Ω |
| Gate-source charge | Q _{gs} * | - | 0.6 | - | nC | I _D = -1.3A R _G =10Ω |
| Gate-drain charge | Q _{gd} * | - | 0.4 | - | nC | V _{GS} = -4.5V |

*Pulsed

●Body diode characteristics (Source-drain) (Ta=25°C)

| Parameter | Symbol | Min. | Typ. | Max. | Unit | Conditions |
|-----------------|-------------------|------|------|------|------|---------------------------------------------|
| Forward voltage | V _{SD} * | - | - | -1.2 | V | I _S = -1.3A, V _{GS} =0V |

*Pulsed

●Electrical characteristics

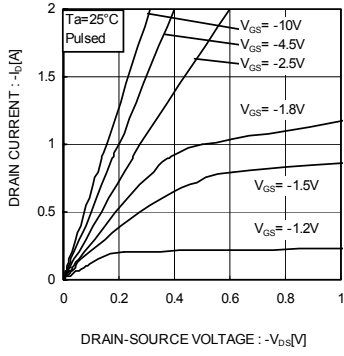


Fig.1 Typical Output Characteristics (I)

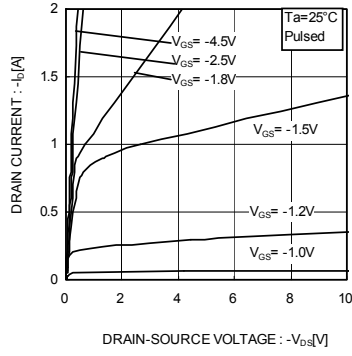


Fig.2 Typical Output Characteristics (II)

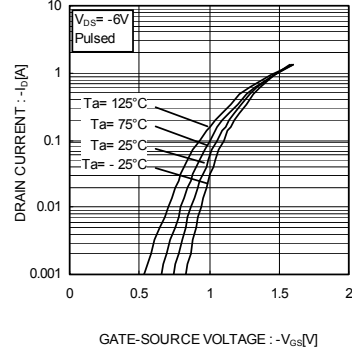


Fig.3 Typical Transfer Characteristics

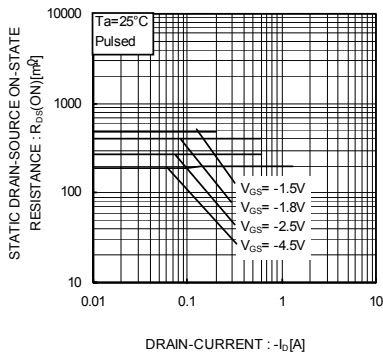


Fig.4 Static Drain-Source On-State Resistance vs. Drain Current (I)

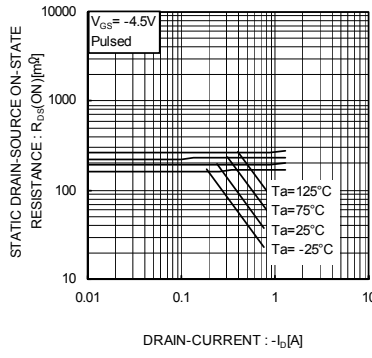


Fig.5 Static Drain-Source On-State Resistance vs. Drain Current (II)

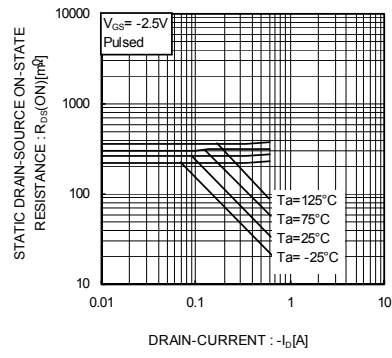


Fig.6 Static Drain-Source On-State Resistance vs. Drain Current (III)

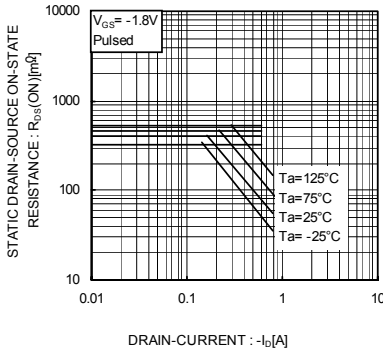


Fig.7 Static Drain-Source On-State Resistance vs. Drain Current (IV)

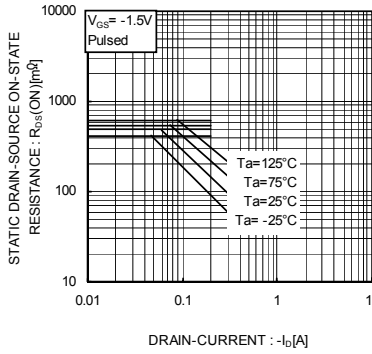


Fig.8 Static Drain-Source On-State Resistance vs. Drain Current (V)

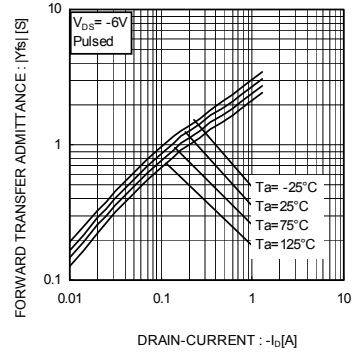


Fig.9 Forward Transfer Admittance vs. Drain Current

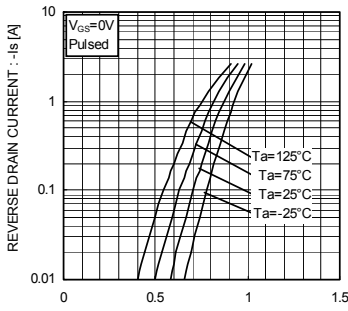


Fig.10 Reverse Drain Current vs. Source-Drain Voltage

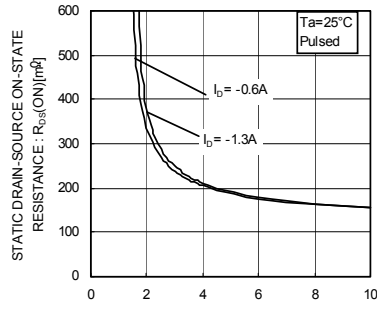


Fig.11 Static Drain-Source On-State Resistance vs. Gate Source Voltage

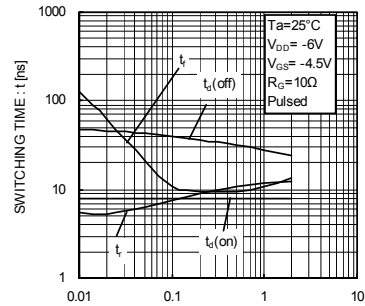


Fig.12 Switching Characteristics

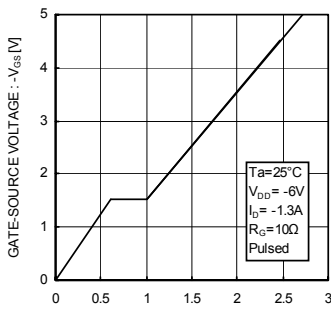


Fig.13 Dynamic Input Characteristics

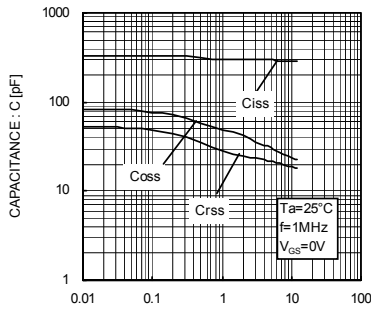


Fig.14 Typical Capacitance vs. Drain-Source Voltage

●Measurement circuits

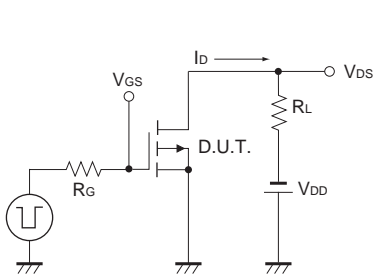


Fig.1-1 Switching time measurement circuit

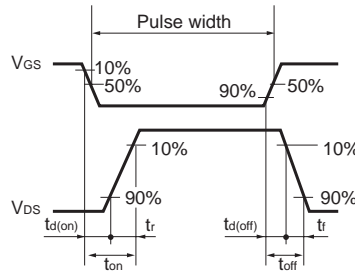


Fig.1-2 Switching waveforms

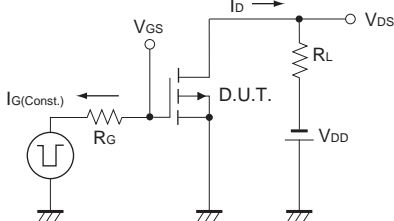


Fig.2-1 Gate charge measurement circuit

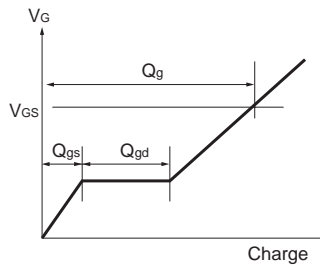


Fig.2-2 Gate charge waveform

●Notice

This product might cause chip aging and breakdown under the large electrified environment . Please consider to design ESD protection circuit.

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